

HIGH-SPEED DIFFERENTIAL LINE DRIVER

FEATURES

- **Designed for Signaling Rates**

NOTE: The signaling rate is the number of voltage transitions that can be made per second.

Up to 150 Mbps

- **Low-Voltage Differential Signaling With Typical Output Voltage of 700 mV and a 100-Ω Load**
- **Propagation Delay Time of 2.3 ns, Typical**
- **Single 3.3-V Supply Operation**
- **One Driver's Power Dissipation at 75 MHz, 50 mW, Typical**
- **High-Impedance Outputs When Disabled or With $V_{CC} < 1.5$ V**
- **Bus-Pin ESD Protection Exceeds 12 kV**
- **Low-Voltage CMOS (LVCMOS) Logic Input Levels Are 5-V Tolerant**

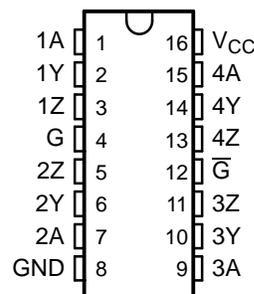
DESCRIPTION

The SN65LVDM31 incorporates four differential line drivers that implement the electrical characteristics of low-voltage differential signaling. This product offers a low-power alternative to 5-V PECL drivers with similar signal levels. Any of the four current-mode drivers will deliver a minimum differential output voltage magnitude of 540 mV into a 100-Ω load when enabled by either an active-low or active-high enable input.

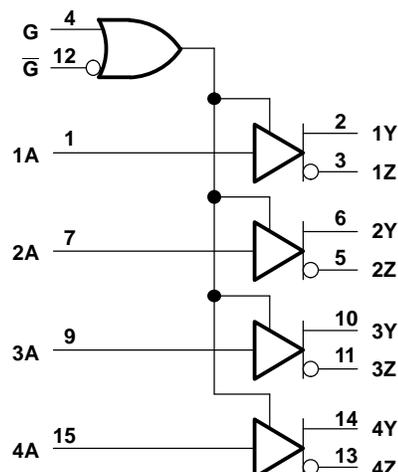
The intended application of this device and signaling technique is for both point-to-point and multiplexed baseband data transmission over controlled impedance media of approximately 100 Ω. The transmission media may be printed-circuit board traces, backplanes, or cables. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media and the noise coupling to the environment.

The SN65LVDM31 is characterized for operation from -40°C to 85°C.

SN65LVDM31D (Marked as LVDM31)
(TOP VIEW)



FUNCTIONAL BLOCK DIAGRAM



FUNCTION TABLE

INPUT	ENABLES		OUTPUTS	
A	G	\bar{G}	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z
Open	H	X	L	H
Open	X	L	L	H

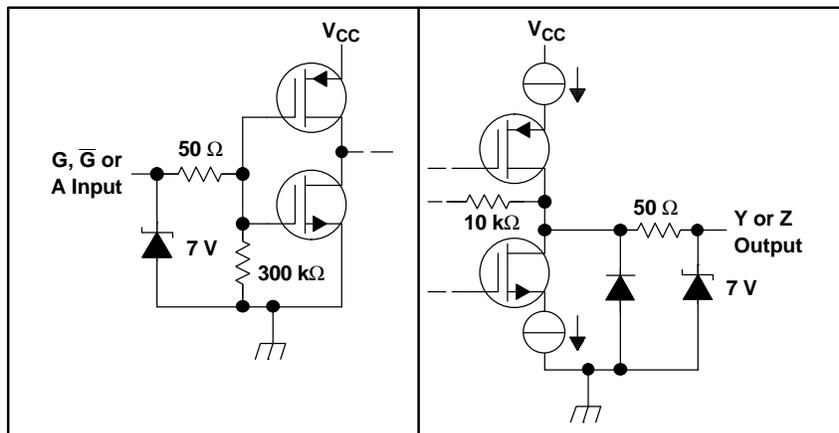


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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		UNIT
Supply voltage range V_{CC} ⁽²⁾		-0.5 V to 4 V
Input voltage range	Inputs	-0.5 V to 6 V
	Y or Z	-0.5 V to 4 V
Electrostatic discharge ⁽³⁾ : Y, Z, and GND		Class 3, A:12 kV, B:600 V
Continuous power dissipation		See Dissipation Rating Table
Storage temperature range		-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		260°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
- (3) Tested in accordance with MIL-STD-883C Method 3015.7.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	OPERATING FACTOR ⁽¹⁾ ABOVE $T_A = 25^\circ\text{C}$	$T_A = 85^\circ\text{C}$ POWER RATING
D	950 mW	7.6 mW/°C	494 mW

- (1) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	3	3.3	3.6	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
T_A	Operating free-air temperature	40		85	°C

ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OD}	Differential output voltage magnitude	R _L = 100 Ω,	See Figure 2	540	700	860	mV
		R _L = 50 Ω,	See Figure 2	270	350	430	
Δ V _{OD}	Change in differential output voltage magnitude between logic states	See Figure 2		-25	0	25	mV
V _{OC(SS)}	Steady-state common-mode output voltage	See Figure 3		1.14	1.2	1.3	V
ΔV _{OC(SS)}	Change in steady-state common-mode output voltage between logic states			-30	0	30	mV
V _{OC(PP)}	Peak-to-peak common-mode output voltage			70	100		
I _{CC}	Supply current	Enabled, No load	V _{IN} = 0 or V _{CC}	6	10	mA	
		Enabled, R _L = 100 Ω		35	40		
		Disabled		0.5	0.7		
I _{IH}	High-level input current	V _{IH} = 3 V		-10	3	10	μA
I _{IL}	Low-level input current	V _{IL} = 0 V		-10	0	10	μA
I _{OS}	Short-circuit output current	V _{OY} or V _{OZ} = 0 V		7	10	mA	
		V _{OD} = 0 V		7	10		
I _{OZ}	High-impedance state output current	V _O = 0 V or V _{CC}		±1		μA	
I _{O(OFF)}	Power-off output current	V _{CC} = 1.5 V,	V _O = 3.6 V	±1		μA	

(1) All typical values are at 25°C and with a 3.3-V supply.

SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low-to-high-level output	See Figure 4	1.8	2.3	2.9	ns
t _{PHL}	Propagation delay time, high-to-low-level output		1.8	2.3	2.9	ns
t _r	Differential output signal rise time		0.4	0.6	1.0	ns
t _f	Differential output signal fall time		0.4	0.6	1.0	ns
t _{sk(p)}	Pulse skew (t _{PHL} - t _{PLH})		50	350	ps	
t _{sk(o)}	Channel-to-channel output skew ⁽¹⁾		200	ps		
t _{sk(pp)}	Part-to-part skew ⁽²⁾	1	ns			
t _{PZH}	Propagation delay time, high-impedance-to-high-level output	See Figure 5	6	15	ns	
t _{PZL}	Propagation delay time, high-impedance-to-low level output		6	15	ns	
t _{PHz}	Propagation delay time, high-level-to-high-impedance output		6	15	ns	
t _{PLz}	Propagation delay time, low-level-to-high-impedance output		6	15	ns	

(1) t_{sk(o)} is the maximum delay time difference between drivers on the same device.

(2) t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

PARAMETER MEASUREMENT INFORMATION

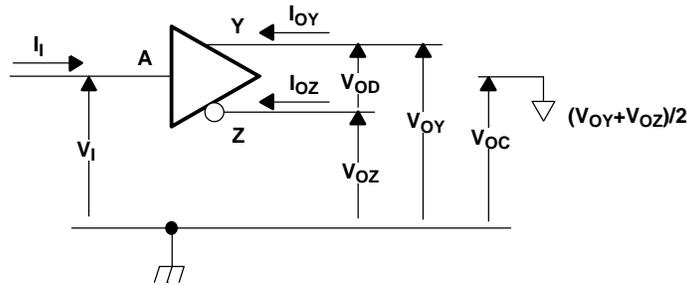


Figure 1. Driver Voltage and Current Definitions

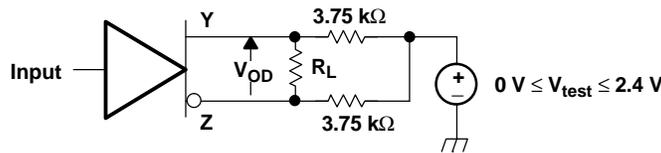
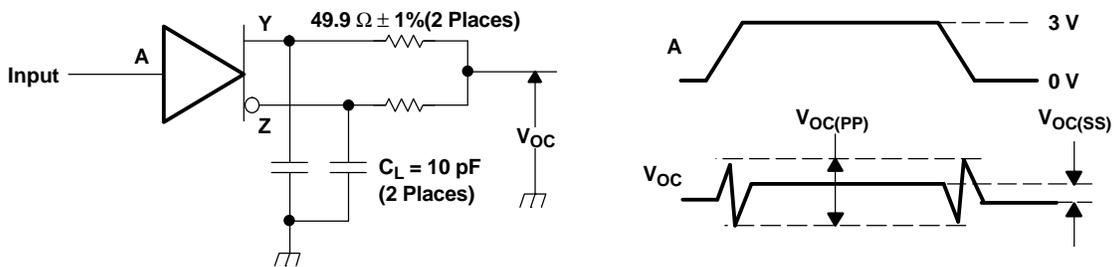
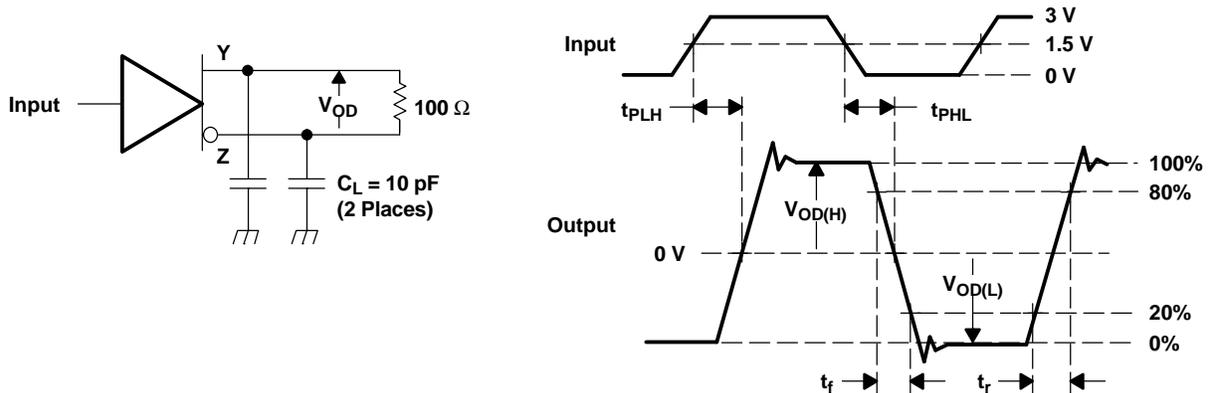


Figure 2. V_{OD} Test Circuit



NOTE: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the DUT. The measurement of $V_{OC(PP)}$ is made on test equipment with a -3 dB bandwidth of at least 300 MHz.

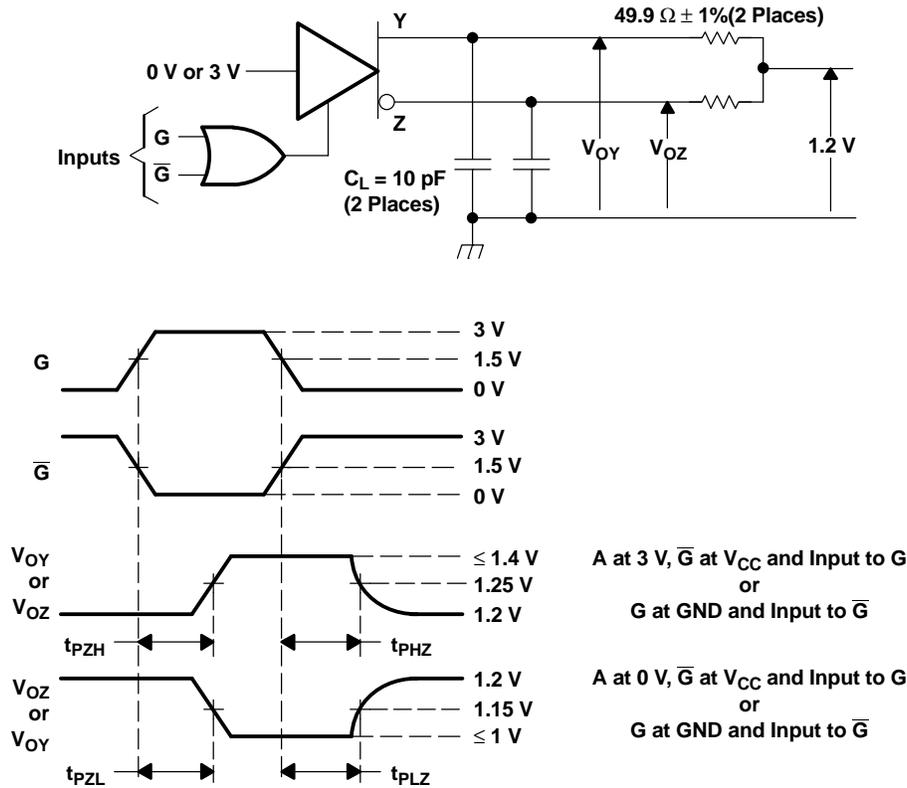
Figure 3. Test Circuit and Definitions for the Driver Common-Mode Output Voltage



NOTE: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the DUT.

Figure 4. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal

PARAMETER MEASUREMENT INFORMATION (continued)



NOTE: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the DUT.

Figure 5. Enable and Disable Time Circuit and Definitions

TYPICAL CHARACTERISTICS

SUPPLY CURRENT
vs
FREQUENCY

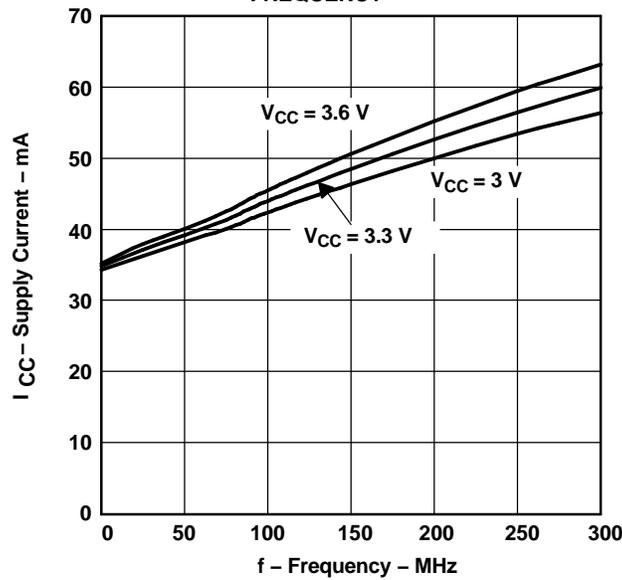


Figure 6.

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

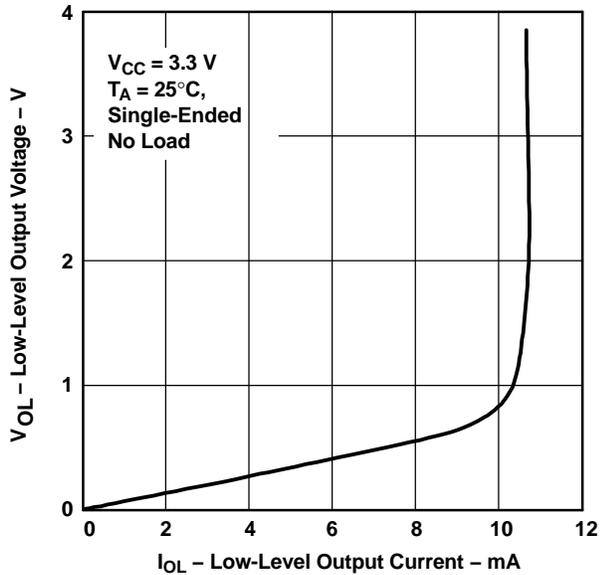


Figure 7.

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

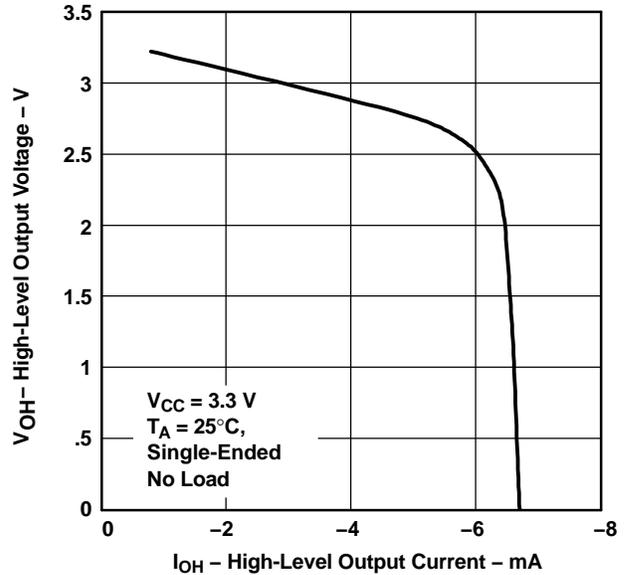
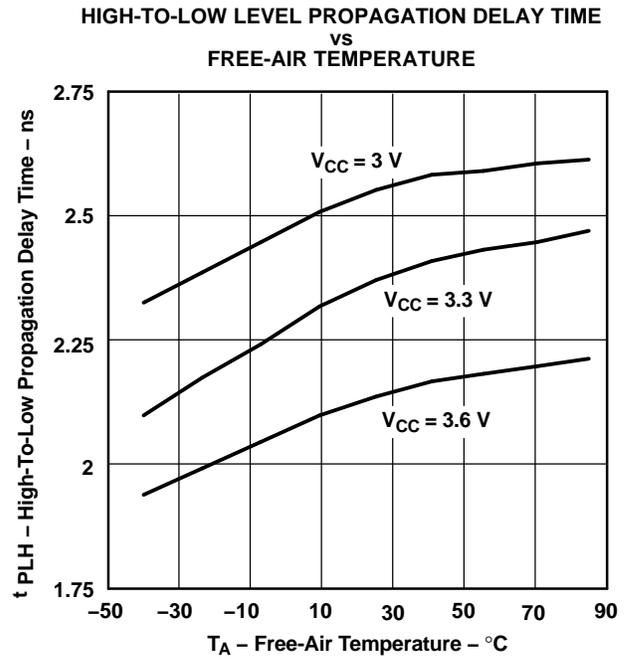
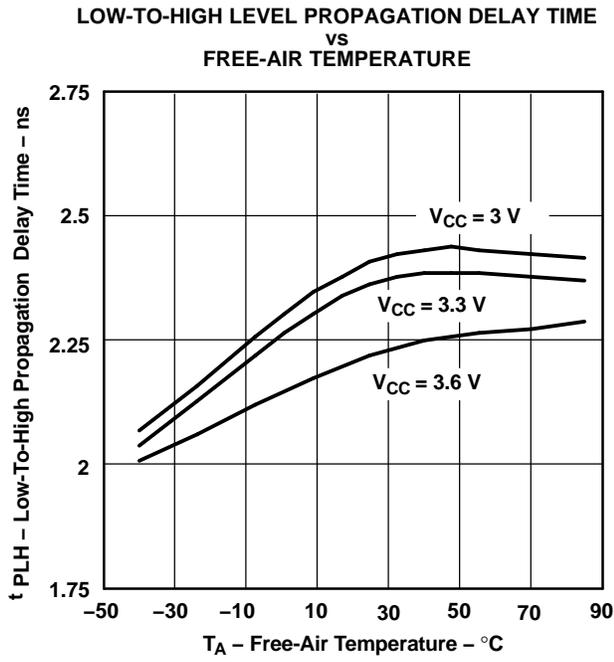


Figure 8.

TYPICAL CHARACTERISTICS (continued)



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LVDM31D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDM31DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDM31DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDM31DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

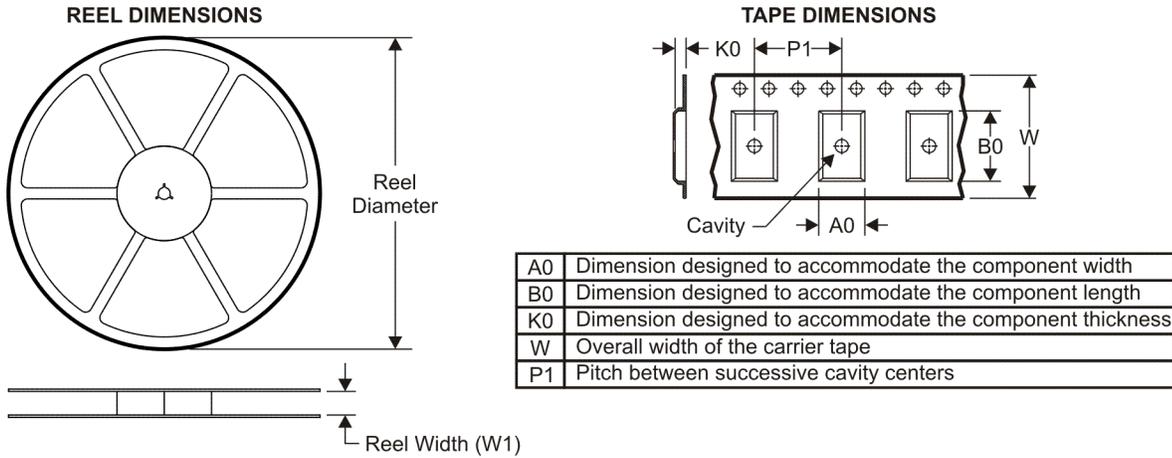
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

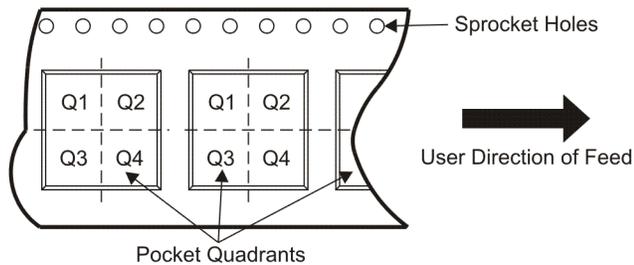
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TAPE AND REEL INFORMATION



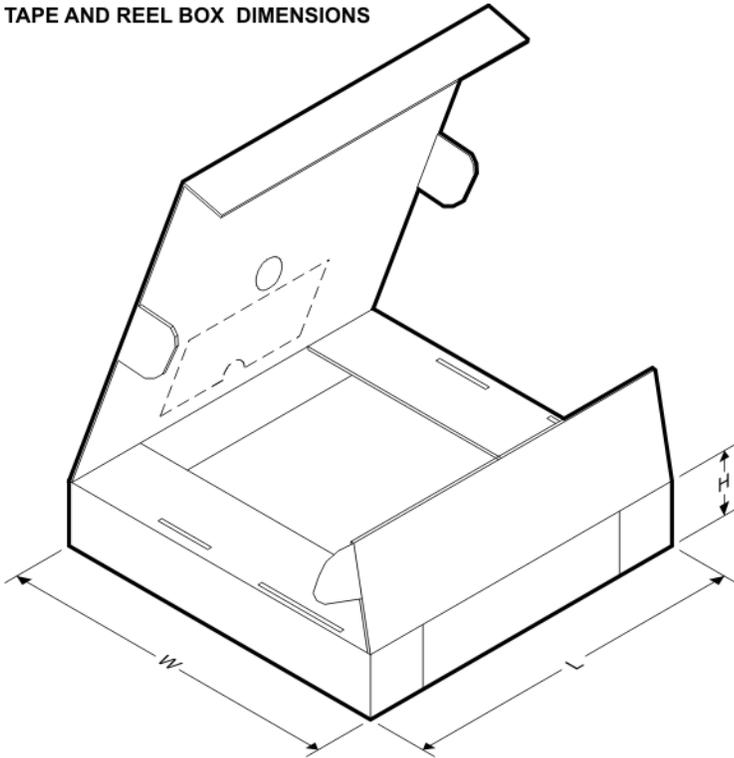
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDM31DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDM31DR	SOIC	D	16	2500	346.0	346.0	33.0

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